



# SOD88A

hermetically sealed glass package; axial leaded; 2 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	A (axial)
<b>Package type descriptive code</b>	GALF2
<b>Package type industry code</b>	GALF2
<b>Package style descriptive code</b>	LALF (glass axial (leaded) long form)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	L (glass)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	20-6-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	8	8	mm
$\Phi$ D	package diameter	[tbd]	-	3.8	3.8	mm
n <sub>2</sub>	actual quantity of termination	-	-	2	-	



## 2. Package outline

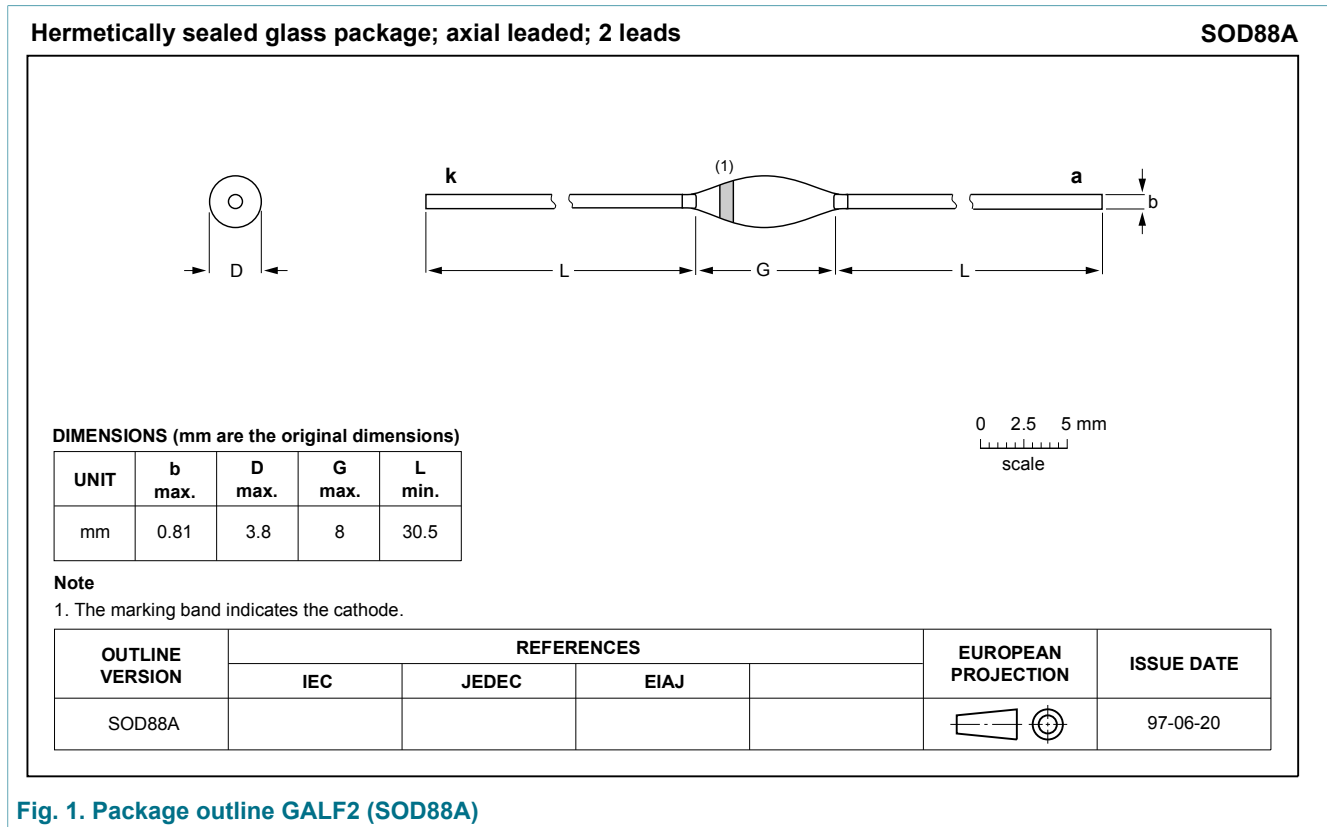


Fig. 1. Package outline GALF2 (SOD88A)

### 3. Legal information

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## 4. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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Date of release: 8 February 2016

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